

MPI TS2000-HP | 200 mm High Power Automated Probe System with ShieldEnvironment™

For accurate High Power measurements up to 10 kV, 600 A

Light Curtain

- Interlock-enabled safety light curtain protects users from accidental high voltage shock

Anti-Arcing Technologies

- ArcShield™ to prevent any possible arcing between the chuck and the probe platen
- The anti-arcing probe card has a capability to apply high-pressure around the DUT and by using the Paschen law to prevent arcing between the pads
- Anti-Arcing LiquidTray™ can be used for arcing suppressing by simply placing it on the high power chuck surface. Wafers can be safely placed inside the tray to submerge in the liquid for arcing free high voltage test

Positioners and High Power Probes

- Supports up to 4 high current or up to 8 high voltage positioners
- Various positioners available
- Dedicated Coax and Triax high voltage and high current probe arms (up to 400 A pulse)

Probe Platen

- Stable and rigid design
- Integrated air-cooling for maximum thermal stability
- Unique access for maintenance and service

ShieldEnvironment™

- Excellent EMI- and light-tight shielded test environment for ultra-low noise, low capacitance measurements
- Front door for manual loading of IC or wafers

Modular Chucks

- Various High Power non-thermal or thermal chucks
- Wide range of temperature from -60 °C up to 300 °C
- Field upgradable for reduced cost of ownership
- MPI's proprietary triaxial connector for ultra-low noise 3kV triaxial and 10kV coaxial set-ups without any changes to the chuck connection

Safety Test Management™ (STM) System

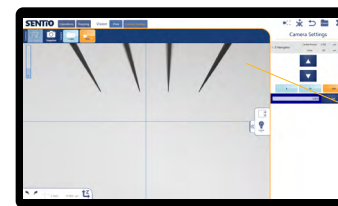
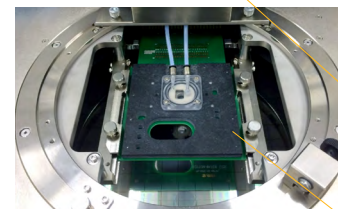
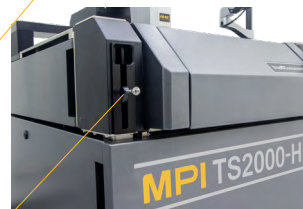
- Provides unique safety, reliable and convenient environment for testing at different temperatures
- Intelligent dew point control routine avoids acumination during cold testing
- Automatically monitoring the flow of CDA or Nitrogen
- If the flow is interrupt or insufficient the STM™ turns the chuck automatically into a safe mode

Probe Hover Control PHC™ Option

- Manual control of probes to wafer contact & separation
- Visual feedback down to 1 μm accuracy in SENTIO®

mDrive™ Option

- Provides a truly intuitive, manual operation of all existing programmable stages, such as chuck, scope or MicroPositioners
- X- and Y-axis fine control for the selected stage
- Z safety function requires additional enabling



Microscope and Optics Options

- Stable microscope bridge mount with 50 x 50 x 140 mm programmable movement
- Various optics options available such as MPI AMZ12 w. up to 12x optical zoom or MPI iMAG® - the digital microscope

Software Suite SENTIO®

- Simple and intuitive operation by revolutionary, multi-touch software control saves significant training time
- Scroll, Zoom, Move commands mimic modern smart mobile devices and allows to become an expert in just minutes
- Switching between the active application and the rest of the APPs is just matter of a simple finger sweep
- MPI RF calibration software program QAlibria® is fully integrated with SENTIO® - for ease of use by following a single operational concept methodology
- GPIB, TCP/IP interface for remote control

Thermal Control

- Thermal chuck can be operated by using the fully integrated touch-screen display placed at convenient location in front of the operator for fast operation and immediate feedback

Automated Single Wafer Loader

- Very convenient wafer loading with easy pre-alignment for automated routines
- Loading or unloading of 100, 150 or 200 mm wafer is straight forward and intuitive

Hot/Cold Wafer Swaps at Set Temperatures

- Unique capability to load/unload wafers at any chuck temperatures
- Saves major down time and increases the overall MPI Test Systems efficiency significantly

Integrated Hardware Control Panel

- Provide faster, safer and convenient system control and test operation
- The Keyboard and mouse are strategically located to control the software if necessary and will also control the Windows® based instrumentation

Active Vibration Isolation

- Incorporates a high performance vibration isolation platform
- Optimized total footprint
- Optional instrument shelf reduces cable lengths and increases measurement dynamic and directivity

Anti-Arcing High Pressure Probe Card

- Up to 10 kV, 600 A high power device testing
- With a maximum of 36 needle pins at down to 50 μm pitch

Vertical Control Environment™ (VCE) Option

- Automated side view of the probe tips - the VCE™ allows contact position automation independent of the probe card tip-drop
- This enables working with probe cards, either DC or RF, very safe, especially inside the MPI ShieldEnvironment™